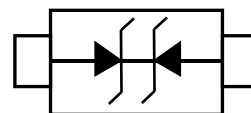


Description

The UMW PESDNC3D5VB protects sensitive semiconductor components from damage or upset due to electrostatic discharge (ESD) and other voltage induced transient events. They feature large cross-sectional area junctions for conducting high transient currents, offer desirable electrical characteristics for board level protection, such as fast response time, low operating voltage. It gives designer the flexibility to protect one bi-directional line in applications where arrays are not practical.



Feature

- 350W peak pulse power per line ($t_P = 8/20\mu s$)
- SOD-323 package
- Replacement for MLV(0805)
- Bidirectional configurations
- Protects one power or I/O port
- Low clamping voltage
- RoHS compliant

Applications

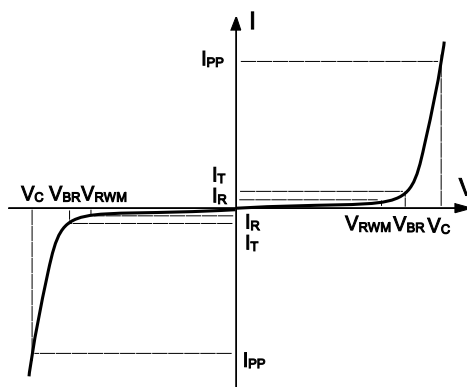
- Laptop computers
- Cellular phones
- Digital cameras
- PDAs

Mechanical Characteristics

- Lead finish: 100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature: $260^\circ C$
- Pure tin plating: $7 \sim 17 \mu m$
- Pin flatness: $\leq 3mil$

Electronics Parameter

Symbol	Parameter
V_{RWM}	Peak Reverse Working Voltage
I_R	Reverse Leakage Current @ V_{RWM}
V_{BR}	Breakdown Voltage @ I_T
I_T	Test Current
I_{PP}	Maximum Reverse Peak Pulse Current
V_C	Clamping Voltage @ I_{PP}
P_{PP}	Peak Pulse Power
C_J	Junction Capacitance
I_F	Forward Current
V_F	Forward Voltage @ I_F



Electrical characteristics per line@25°C(unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Peak Reverse Working Voltage	V_{RWM}				5	V
Breakdown Voltage	V_{BR}	$I_t = 1mA$	6		8	V
Reverse Leakage Current	I_R	$V_{RWM} = 5V$ $T=25^{\circ}C$			1.0	μA
Clamping Voltage	V_C	$I_{PP} = 1A$ $t_P = 8/20\mu s$			9.2	V
Clamping Voltage	V_C	$I_{PP}=5A$ $t_P = 8/20\mu s$			11	V
Clamping Voltage	V_C	$I_{PP}=24A$ $t_P = 8/20\mu s$			23	V
Junction Capacitance	C_j	$V_R=0V$ $f = 1MHz$		85		pF

Absolute maximum rating@25°C

Rating	Symbol	Value	Units
Unidirectional Peak Pulse Power	P_{pp}	350	W
Operating Temperature	T_J	-55 to +150	$^{\circ}C$
Storage Temperature	T_{STG}	-55 to +150	$^{\circ}C$

Typical Characteristics

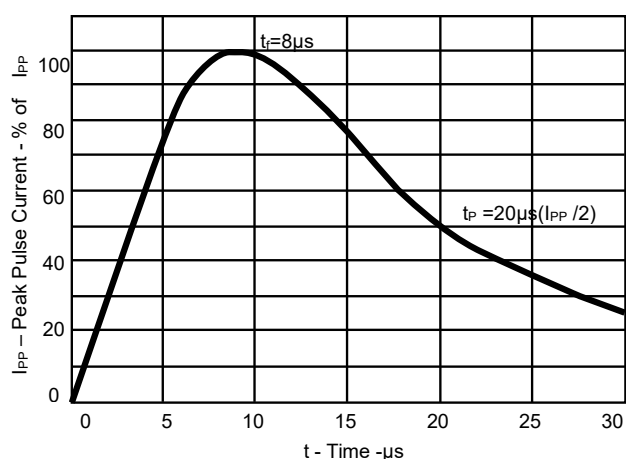


Fig 1.Pulse Waveform

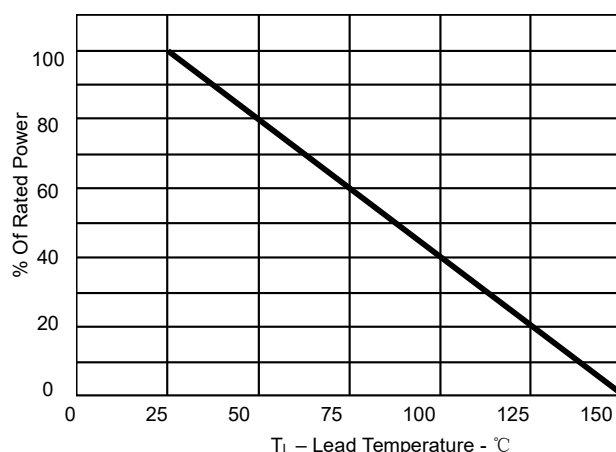


Fig 2.Power Derating Curve

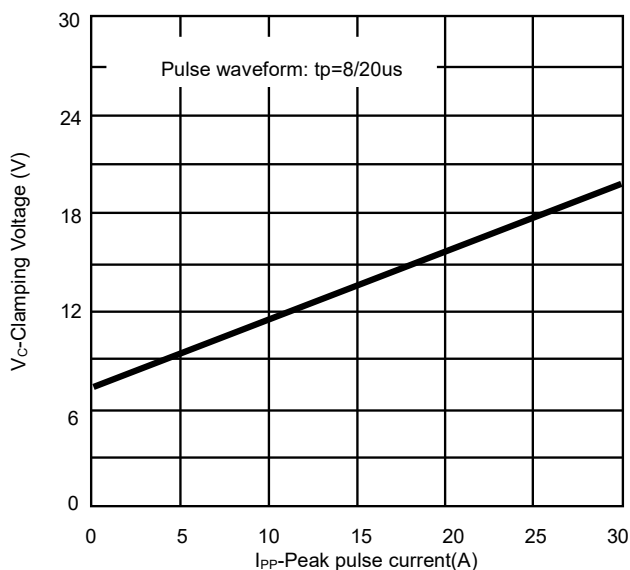


Fig 3. Clamping voltage vs. Peak pulse current

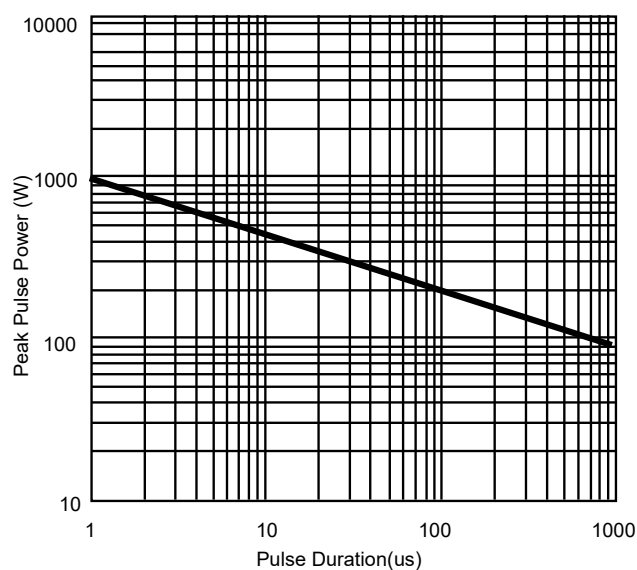
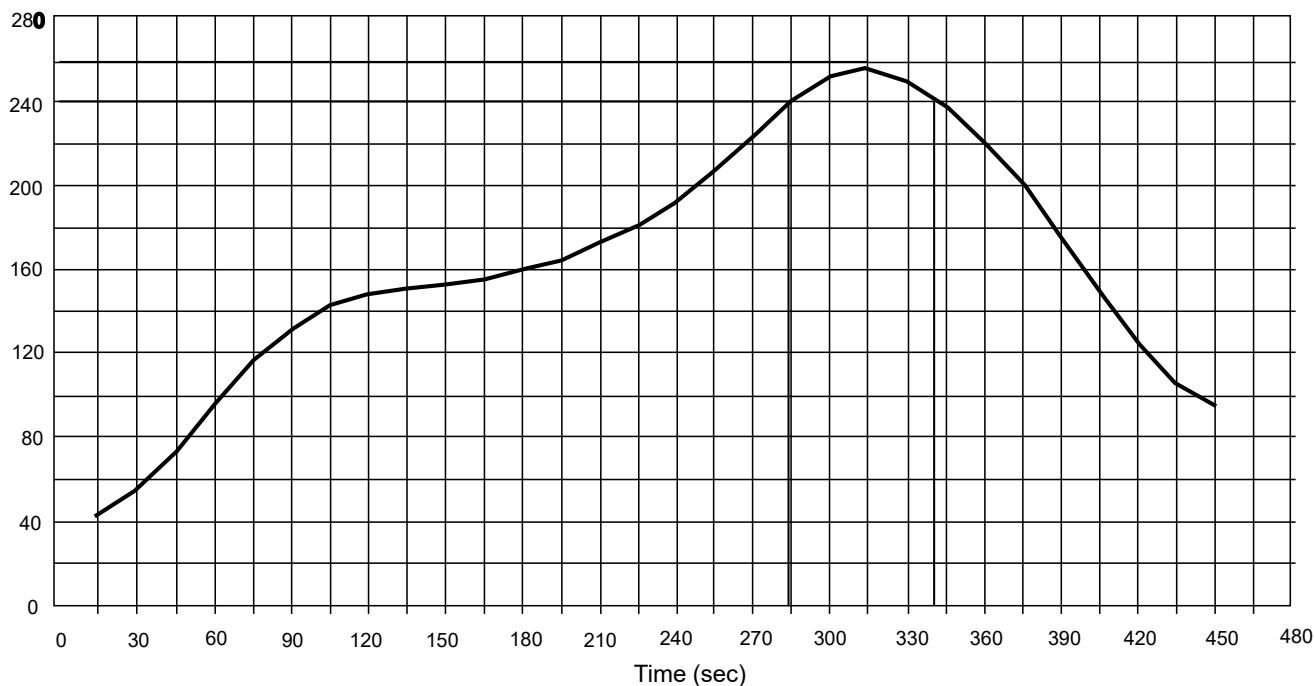


Fig 4. Non Repetitive Peak Pulse Power vs. Pulse time

Solder Reflow Recommendation

Peak Temp=257°C, Ramp Rate=0.802deg. °C/sec

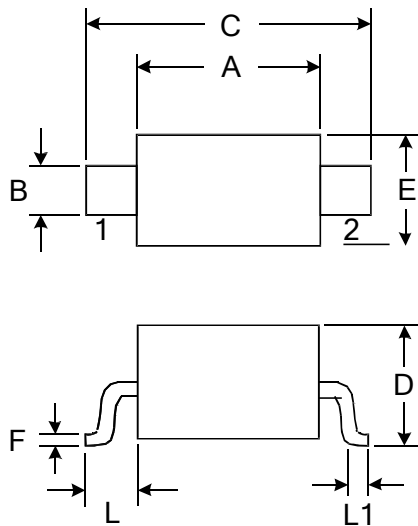


PCB Design

For TVS diodes a low-ohmic and low-inductive path to chassis earth is absolutely mandatory in order to achieve good ESD protection. Novices in the area of ESD protection should take following suggestions to heart:

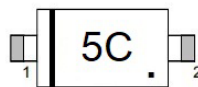
- Do not use stubs, but place the cathode of the TVS diode directly on the signal trace.
- Do not make false economies and save copper for the ground connection.
- Place via holes to ground as close as possible to the anode of the TVS diode.
- Use as many via holes as possible for the ground connection.
- Keep the length of via holes in mind! The longer the more inductance they will have.

Outline Drawing – SOD-323



DIMENSIONS				
SYMBOL	MILLIMETER		INCHES	
	MIN	MAX	MIN	MAX
A	1.600	1.800	0.063	0.071
B	0.250	0.350	0.010	0.014
C	2.500	2.700	0.098	0.106
D		1.000		0.039
E	1.200	1.400	0.047	0.055
F	0.080	0.150	0.003	0.006
L	0.475 REF		0.019REF	
L1	0.250	0.400	0.010	0.016
H	0.000	0.100	0.000	0.004

Marking



Ordering information

Order code	Package	Baseqty	Deliverymode
UMW PESDNC3D5VB	SOD-323	3000	Tape and reel